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- Product picture -

FEATURES:

- Soft, excellent compression performance
- Low thermal resistance
- Being recognized as UL94 V-0
- Viscous surface
- Being able to work under low pressure
- Excellent insulation performance and thermal resistance

APPLICATIONS:

- Between chip and heat-dissipation modules
- Optoelectronic Industry
- Netcom products
- New energy battery and vehicles industry
- Household appliances
- Wearable equipments

The series of products are accord with standards of RoHS and HALOGEN.

STORAGE CONDITIONS: Storage in the darkness

STORAGE TEMPERATURE: $\leq 30\text{ }^{\circ}\text{C}$

STORAGE HUMIDITY: $\leq 70\%$

The height of the stacking should not be more than 7 layers and the total height should not be more than 1m.

SHELF LIFE: Two years at storage conditions

Thermal gap filler has excellent flexibility insulation, compressibility and natural surface viscosity performances. It used to fill the gap and realize the heat transfer between the heating parts and cooling parts. It also has insulation and shock mitigation effects. Meanwhile, it can satisfy the design requirements for minitype and ultra-thin equipments with excellent manufacturability and practicability. With wide range of thickness, it is widely used in electronic products.

PROPERTIES

Items	Parameter	Unit	Test Method
Color	Gray White	-	Visual
Thickness	0.2~18	mm	ASTM D 374
Hardness	8~60(± 5)	Shore C	ASTM D 2240
Density	2.35(± 0.5)	g/cc	ASTM D 792
Tensile Strength	≥ 0.3	Mpa	ASTM D 412
Elongation	≥ 80	%	ASTM D 412
Compression Ratio	≥ 25 (@50Psi)	%	ASTM D 575
UL Certification	V-0,5V	-	UL94
Operating Temperature	-50~200	$^{\circ}\text{C}$	IEC 60068-2-14

THERMAL CHARACTERISTIC

Thermal Conductivity	1.0(± 0.2)	W/m·K	ASTM D 5470
Thermal Resistance	≤ 2.0 (@20Psi/1mm)	$^{\circ}\text{Cin}^2/\text{W}$	ASTM D 5470

ELECTRICAL PROPERTIES

Breakdown Voltage	≥ 8 (@1mm)	KV	ASTM D 149
Volume Resistivity	$\geq 10^8$	$\Omega\text{-cm}$	ASTM D 257

All above data are copyrighted and elaborated by HFC

APPLICATION METHOD:

Thermal Gap Filler must be compressed to make up for device tolerances and to remove air from the interface when it is used, so our interface material can has good contact with both the heat dissipating component and the heat generating component. In general, there are three kinds of compression for the interface material:

1. When the hardness is less than Shore C 20, it is recommended to use 30% to 40% of the compression.
2. When the hardness between Shore C 20 to Shore C 40, it is recommended to use 25% to 30% of the compression.
3. When the hardness is more than Shore C 40, it is recommended to use 20% of the compression.

HFC H100-Soft series

【 Thermal Gap Filler 】

DATA SHEET



- Product picture -

FEATURES:

- Ultra-soft, excellent compression performance
- Low thermal resistance
- Being recognized as UL94 V-0
- Viscous surface
- Being able to work under low pressure
- Excellent insulation performance and

APPLICATIONS:

- Between chip and heat-dissipation modules
- Optoelectronic Industry
- Netcom products
- New energy battery and vehicles industry
- Household appliances
- Wearable equipments

The series of products are accord with standards of RoHS and HALOGEN.

STORAGE CONDITIONS: Storage in the darkness

STORAGE TEMPERATURE: $\leq 30\text{ }^{\circ}\text{C}$

STORAGE HUMIDITY: $\leq 70\%$

The height of the stacking should not be more than 7 layers and the total height should not be more than 1m.

SHELF LIFE: Two years at storage conditions

Thermal gap filler has excellent flexibility insulation, compressibility and natural surface viscosity performances. It used to fill the gap and realize the heat transfer between the heating parts and cooling parts. It also has insulation and shock mitigation effects. Meanwhile, it can satisfy the design requirements for minitype and ultra-thin equipments with excellent manufacturability and practicability. With wide range of thickness, it is widely used in electronic products.

PROPERTIES

Items	Parameter	Unit	Test Method
Color	White	-	Visual
Carriers	Sil-pad/Insulation-pad	-	-
Thickness	1.5~3	mm	ASTM D 374
Hardness	10(± 5)	Shore C	ASTM D 2240
Density	2.35(± 0.5)	g/cc	ASTM D 792
Tensile Strength	≥ 1.5	Mpa	ASTM D 412
Elongation	≥ 5	%	ASTM D 412
Compression Ratio	≥ 40 (@50Psi)	%	ASTM D 575
UL Certification	V-0,5V	-	UL94
Operating Temperature	-50~200	$^{\circ}\text{C}$	IEC 60068-2-14

THERMAL CHARACTERISTIC

Thermal Conductivity	1.0(± 0.2)	W/m-K	ASTM D 5470
Thermal Resistance	≤ 3.0 (@20Psi/1mm)	$^{\circ}\text{Cin}^2/\text{W}$	ASTM D 5470

ELECTRICAL PROPERTIES

Breakdown Voltage	≥ 8 (@1mm)	KV	ASTM D 149
Volume Resistivity	$\geq 10^8$	$\Omega\text{-cm}$	ASTM D 257

All above data are copyrighted and elaborated by HFC

APPLICATION METHOD:

Thermal Gap Filler must be compressed to make up for device tolerances and to remove air from the interface when it is used, so our interface material can have good contact with both the heat dissipating component and the heat generating component. In general, there are three kinds of compression for the interface material:

1. When the hardness is less than Shore C 20, it is recommended to use 30% to 40% of the compression.
2. When the hardness between Shore C 20 to Shore C 40, it is recommended to use 25% to 30% of the compression.
3. When the hardness is more than Shore C 40, it is recommended to use 20% of the compression.

HFC H150 series

【 Thermal Gap Filler 】

DATA SHEET



- Product picture -

FEATURES:

- Soft, excellent compression performance
- Low thermal resistance
- Being recognized as UL94 V-0
- Viscous surface
- Being able to work under low pressure
- Excellent insulation performance and thermal resistance

APPLICATIONS:

- Between chip and heat-dissipation modules
- Optoelectronic Industry
- Netcom products
- New energy battery and vehicles industry
- Household appliances
- Wearable equipments

The series of products are accord with standards of RoHS and HALOGEN.

STORAGE CONDITIONS: Storage in the darkness

STORAGE TEMPERATURE: $\leq 30\text{ }^{\circ}\text{C}$

STORAGE HUMIDITY: $\leq 70\%$

The height of the stacking should not be more than 7 layers and the total height should not be more than 1m.

SHELF LIFE: Two years at storage conditions

Thermal gap filler has excellent flexibility insulation, compressibility and natural surface viscosity performances. It used to fill the gap and realize the heat transfer between the heating parts and cooling parts. It also has insulation and shock mitigation effects. Meanwhile, it can satisfy the design requirements for minitype and ultra-thin equipments with excellent manufacturability and practicability. With wide range of thickness, it is widely used in electronic products.

PROPERTIES

Items	Parameter	Unit	Test Method
Color	Pink	-	Visual
Thickness	0.3~18	mm	ASTM D 374
Hardness	10~55(±5)	Shore C	ASTM D 2240
Density	2.62(±0.5)	g/cc	ASTM D 792
Tensile Strength	≥ 0.25	Mpa	ASTM D 412
Elongation	≥ 80	%	ASTM D 412
Compression Ratio	≥ 25 (@50Psi)	%	ASTM D 575
UL Certification	V-0,5V	-	UL94
Operating Temperature	-50~200	$^{\circ}\text{C}$	IEC 60068-2-14

THERMAL CHARACTERISTIC

Thermal Conductivity	1.5(±0.2)	W/m·K	ASTM D 5470
Thermal Resistance	≤ 1.5 (@20Psi/1mm)	$^{\circ}\text{Cin}^2/\text{W}$	ASTM D 5470

ELECTRICAL PROPERTIES

Breakdown Voltage	≥ 8 (@1mm)	KV	ASTM D 149
Volume Resistivity	$\geq 10^8$	$\Omega\cdot\text{cm}$	ASTM D 257

All above data are copyrighted and elaborated by HFC

APPLICATION METHOD:

Thermal Gap Filler must be compressed to make up for device tolerances and to remove air from the interface when it is used, so our interface material can have good contact with both the heat dissipating component and the heat generating component. In general, there are three kinds of compression for the interface material:

1. When the hardness is less than Shore C 20, it is recommended to use 30% to 40% of the compression.
2. When the hardness between Shore C 20 to Shore C 40, it is recommended to use 25% to 30% of the compression.
3. When the hardness is more than Shore C 40, it is recommended to use 20% of the compression.

HFC H150-A series

【 Thermal Gap Filler 】

DATA SHEET



- Product picture -

FEATURES:

- Strength and excellent toughness
- High resilience
- UL94 V-O recognized
- High insulation
- High tear strength

APPLICATIONS:

- New energy battery and vehicles industry
- Between chip and heat-dissipation modules
- Optoelectronic Industry
- Netcom products
- Wearable equipments

The series of products are accord with standards of RoHS and HALOGEN.

STORAGE CONDITIONS: Storage in the darkness

STORAGE TEMPERATURE: $\leq 30\text{ }^{\circ}\text{C}$

STORAGE HUMIDITY: $\leq 70\%$

The height of the stacking should not be more than 7 layers and the total height should not be more than 1m.

SHELF LIFE: Two years at storage conditions

Thermal gap filler has excellent flexibility,insulation,compressibility and natural surface viscosity performances.It used to fill the gap and realize the heat transfer between the heating parts and cooling parts.It also has insulation and shock mitigation effects.Meanwhile,it can satisfy the design requirements for minitype and ultra-thin equipments with excellent manufacturability and practicability.With wide range of thickness,it is widely used in electronic products.

PROPERTIES

Items	Parameter	Unit	Test Method
Color	Light yellow/Gray	-	Visual
Thickness	1~4	mm	ASTM D 374
Hardness	10~15	Shore C	ASTM D 2240
Density	2.15(± 0.2)	g/cc	ASTM D 792
Tensile Strength	≥ 0.4	Mpa	ASTM D 412
Elongation	≥ 150	%	ASTM D 412
Tear Strength	≥ 2.5	KN/m	ASTM D 624
compression resilience rate	≥ 75	%	ASTM D 395
Compression Ratio	≥ 25 (@50Psi)	%	ASTM D 575
UL Certification	V-0	-	UL94
Operating Temperature	-50~180	$^{\circ}\text{C}$	IEC 60068-2-14

THERMAL CHARACTERISTIC

Thermal Conductivity	≥ 1.2	W/m·K	ASTM D 5470
Thermal Resistance	≤ 1.5 (@20Psi/1mm)	$^{\circ}\text{Cin}^2/\text{W}$	ASTM D 5470

ELECTRICAL PROPERTIES

Breakdown Voltage	≥ 10 (@1mm)	KV	ASTM D 149
Volume Resistivity	$\geq 10^{10}$	$\Omega\cdot\text{cm}$	ASTM D 257

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APPLICATION METHOD:

Thermal Gap Filler must be compressed to make up for device tolerances and to remove air from the interface when it is used, so our interface material can has good contact with both the heat dissipating component and the heat generating component. In general, there are three kinds of compression for the interface material:

1. When the hardness is less than Shore C 20, it is recommended to use 30% to 40% of the compression.
2. When the hardness between Shore C 20 to Shore C 40, it is recommended to use 25% to 30% of the compression.
3. When the hardness is more than Shore C 40, it is recommended to use 20% of the compression.

HFC H150-S series

【 Thermal Gap Filler 】

DATA SHEET



- Product picture -

FEATURES:

- Strength and excellent toughness
- High resilience
- High insulation
- High tear strength

APPLICATIONS:

- New energy battery and vehicles industry
- Between chip and heat-dissipation modules
- Optoelectronic industry
- Netcom products
- Wearable equipments

The series of products are accord with standards of RoHS and HALOGEN.

STORAGE CONDITIONS: Storage in the darkness

STORAGE TEMPERATURE: $\leq 30\text{ }^{\circ}\text{C}$

STORAGE HUMIDITY: $\leq 70\%$

The height of the stacking should not be more than 7 layers and the total height should not be more than 1m.

SHELF LIFE: Two years at storage conditions

Thermal gap filler has excellent flexibility,insulation,compressibility and natural surface viscosity performances.It used to fill the gap and realize the heat transfer between the heating parts and cooling parts.It also has insulation and shock mitigation effects Meanwhile,it can satisfy the design requirements for minitype and ultra-thin equipments with excellent manufacturability and practicability.With wide range of thickness,it is widely used in electronic products.

PROPERTIES

Items	Parameter	Unit	Test Method
Color	Gray	-	Visual
Thickness	1~2.5	mm	ASTM D 374
Hardness	35(± 5)	Shore C	ASTM D 2240
Density	2.4(± 0.2)	g/cc	ASTM D 792
Tensile Strength	≥ 0.35	Mpa	ASTM D 412
Elongation	≥ 150	%	ASTM D 412
Tear Strength	≥ 1.2	KN/m	ASTM D 624
compression resilience rate	≥ 75	%	ASTM D 395
Compression Ratio	≥ 20 (@50Psi)	%	ASTM D 575
UL Certification	V-0	-	UL94
Operating Temperature	-50~180	$^{\circ}\text{C}$	IEC 60068-2-14

THERMAL CHARACTERISTIC

Thermal Conductivity	1.5(± 0.2)	W/m·K	ASTM D 5470
Thermal Resistance	≤ 1.5 (@20Psi/1mm)	$^{\circ}\text{Cin}^2/\text{W}$	ASTM D 5470

ELECTRICAL PROPERTIES

Breakdown Voltage	≥ 10 (@1mm)	KV	ASTM D 149
Volume Resistivity	$\geq 10^{10}$	$\Omega\cdot\text{cm}$	ASTM D 257

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APPLICATION MATHOD:

Thermal Gap Filler must be compressed to make up for device tolerances and to remove air from the interface when it is used, so our interface material can has good contact with both the heat dissipating component and the heat generating component. In general, there are three kinds of compression for the interface material:

1. When the hardness is less than Shore C 20, it is recommended to use 30% to 40% of the compression.
2. When the hardness between Shore C 20 to Shore C 40, it is recommended to use 25% to 30% of the compression.
3. When the hardness is more than Shore C 40, it is recommended to use 20% of the compression.

HFC H150-LD series

【 Thermal Gap Filler 】

DATA SHEET



- Product picture -

The product's density is 1.6~1.8g/cc, which is 30% lower than the conventional thermal pad. It also has high strength, low permanent deformation and good flame retardancy. It is the best choice for lightweight PACK.

PROPERTIES

Items	Parameter	Unit	Test Method
Color	Gray	-	Visual
Thickness	1~3	mm	ASTM D 374
Hardness	45(±5)	Shore C	ASTM D 2240
Density	1.65(±0.15)	g/cc	ASTM D 792
Tensile Strength	≥0.30	Mpa	ASTM D 412
Elongation	≥200	%	ASTM D 412
Compression Ratio	≥20(@50Psi)	%	ASTM D 575
UL Certification	V-0	-	UL94
Operating Temperature	-50~180	°C	IEC 60068-2-14

THERMAL CHARACTERISTIC

Thermal Conductivity	1.2(±0.2)	W/m·K	ASTM D 5470
Thermal Resistance	≤2.0(@20Psi/1mm)	°Cin ² /W	ASTM D 5470

ELECTRICAL PROPERTIES

Breakdown Voltage	≥10(@1mm)	KV	ASTM D 149
Volume Resistivity	≥10 ¹⁰	Ω·cm	ASTM D 257

All above data are copyrighted and elaborated by HFC

FEATURES:

- Soft, excellent compression performance
- Low thermal resistance
- Being recognized as UL94 V-0
- Viscous surface
- Being able to work under low pressure
- Excellent insulation performance and thermal resistance

APPLICATIONS:

- Between chip and heat-dissipation modules
- Optoelectronic Industry
- Netcom products
- New energy battery and vehicles industry
- Household appliances
- Wearable equipments

The series of products are accord with standards of RoHS and HALOGEN.

STORAGE CONDITIONS: Storage in the darkness

STORAGE TEMPERATURE: ≤ 30 °C

STORAGE HUMIDITY: ≤ 70%

The height of the stacking should not be more than 7 layers and the total height should not be more than 1m.

SHELF LIFE: Two years at storage conditions

APPLICATION METHOD:

Thermal Gap Filler must be compressed to make up for device tolerances and to remove air from the interface when it is used, so our interface material can have good contact with both the heat dissipating component and the heat generating component. In general, there are three kinds of compression for the interface material:

1. When the hardness is less than Shore C 20, it is recommended to use 30% to 40% of the compression.
2. When the hardness between Shore C 20 to Shore C 40, it is recommended to use 25% to 30% of the compression.
3. When the hardness is more than Shore C 40, it is recommended to use 20% of the compression.

DATA SHEET



- Product picture -

FEATURES:

- Soft, excellent compression performance
- Low thermal resistance
- Being recognized as UL94 V-0
- Viscous surface
- Being able to work under low pressure
- Excellent insulation performance and thermal resistance

APPLICATIONS:

- Between chip and heat-dissipation modules
- Optoelectronic Industry
- Netcom products
- New energy battery and vehicles industry
- Household appliances
- Wearable equipments

The series of products are accord with standards of RoHS and HALOGEN.

STORAGE CONDITIONS: Storage in the darkness

STORAGE TEMPERATURE: $\leq 30\text{ }^{\circ}\text{C}$

STORAGE HUMIDITY: $\leq 70\%$

The height of the stacking should not be more than 7 layers and the total height should not be more than 1m.

SHELF LIFE: Two years at storage conditions

Thermal gap filler has excellent flexibility insulation, compressibility and natural surface viscosity performances. It used to fill the gap and realize the heat transfer between the heating parts and cooling parts. It also has insulation and shock mitigation effects. Meanwhile, it can satisfy the design requirements for minitype and ultra-thin equipments with excellent manufacturability and practicability. With wide range of thickness, it is widely used in electronic products.

PROPERTIES

Items	Parameter	Unit	Test Method
Color	Light Blue	-	Visual
Thickness	0.3~18	mm	ASTM D 374
Hardness	10~55(±5)	Shore C	ASTM D 2240
Density	2.8(±0.5)	g/cc	ASTM D 792
Tensile Strength	≥ 0.25	Mpa	ASTM D 412
Elongation	≥ 70	%	ASTM D 412
Compression Ratio	≥ 25 (@50Psi)	%	ASTM D 575
UL Certification	V-0,5V	-	UL94
Operating Temperature	-50~200	$^{\circ}\text{C}$	IEC 60068-2-14

THERMAL CHARACTERISTIC

Thermal Conductivity	2.0(±0.2)	W/m·K	ASTM D 5470
Thermal Resistance	≤ 1.2 (@20Psi/1mm)	$^{\circ}\text{Cin}^2/\text{W}$	ASTM D 5470

ELECTRICAL PROPERTIES

Breakdown Voltage	≥ 8 (@1mm)	KV	ASTM D 149
Volume Resistivity	$\geq 10^8$	$\Omega\text{-cm}$	ASTM D 257

All above data are copyrighted and elaborated by HFC

APPLICATION MATHOD:

Thermal Gap Filler must be compressed to make up for device tolerances and to remove air from the interface when it is used, so our interface material can has good contact with both the heat dissipating component and the heat generating component. In general, there are three kinds of compression for the interface material:

1. When the hardness is less than Shore C 20, it is recommended to use 30% to 40% of the compression.
2. When the hardness between Shore C 20 to Shore C 40, it is recommended to use 25% to 30% of the compression.
3. When the hardness is more than Shore C 40, it is recommended to use 20% of the compression.

HFC H200-Soft series

【 Thermal Gap Filler 】

DATA SHEET



- Product picture -

HFC H200-soft series thermal gap filler is a thermal conductive interface material with natural surface viscosity. The product has low thermal resistance, good flexibility and electrical insulation. The product is of natural stickiness and high compressibility, which can fill the gap well and realize the heat transfer from the heating part to the heat dissipation part. At the same time, it also plays the role of insulation and damping, which can meet the design requirements of miniaturization and ultra-thin equipment. It is highly technically usable.

FEATURES:

- Ultra-soft, excellent compression rate
- Low Thermal Impedance
- UL94 V-0 recognized
- Surface with viscous
- Working under low pressure
- Excellent electrical insulation performance and heat resistance

APPLICATIONS:

- Between chip and heat-dissipation modules
- Optoelectronic Industry
- Netcom products
- New energy Battery and Vehicles Industry
- Household appliances
- Wearable equipment

The series of products are accord with standards of RoHS and HALOGEN.

STORAGE CONDITIONS: Storage in the darkness

STORAGE TEMPERATURE: $\leq 30\text{ }^{\circ}\text{C}$

STORAGE HUMIDITY: $\leq 70\%$

The height of the stacking should not be more than 7 layers and the total height should not be more than 1m.

SHELF LIFE: Two years at storage conditions

PROPERTIES

Items	Parameter	Unit	Test Method
Color	Light Blue	-	Visual
Thickness	0.8~3	mm	ASTM D 374
Hardness	20(± 5)	Shore 00	ASTM D 2240
Density	2.4(± 0.5)	g/cc	ASTM D 792
Tensile Strength	≥ 0.15	Mpa	ASTM D 412
Elongation	≥ 70	%	ASTM D 412
Compression Ratio	≥ 50 (@50Psi)	%	ASTM D 575
UL Certification	V-0,5V	-	UL94
Operating Temperature	-50~180	$^{\circ}\text{C}$	IEC 60068-2-14

THERMAL CHARACTERISTIC

Thermal Conductivity	2.0(± 0.3)	W/m·K	ASTM D 5470
Thermal Resistance	≤ 0.7 (@20Psi/1mm)	$^{\circ}\text{Cin}^2/\text{W}$	ASTM D 5470

ELECTRICAL PROPERTIES

Breakdown Voltage	≥ 8	KV	ASTM D 149
Volume Resistivity	$\geq 10^8$	$\Omega\text{-cm}$	ASTM D 257

All above data are copyrighted and elaborated by HFC

APPLICATION METHOD:

Thermal Gap Filler must be compressed to make up for device tolerances and to remove air from the interface when it is used, so our interface material can has good contact with both the heat dissipating component and the heat generating component. In general, there are three kinds of compression for the interface material:

1. When the hardness is less than Shore C 20, it is recommended to use 30% to 40% of the compression.
2. When the hardness between Shore C 20 to Shore C 40, it is recommended to use 25% to 30% of the compression.
3. When the hardness is more than Shore C 40, it is recommended to use 20% of the compression.

DATA SHEET



- Product picture -

FEATURES:

- Soft, excellent compression performance
- Low thermal resistance
- Being recognized as UL94 V-0
- Viscous surface
- Being able to work under low pressure
- Excellent insulation performance and thermal resistance

APPLICATIONS:

- Between chip and heat-dissipation modules
- Optoelectronic Industry
- Netcom products
- New energy battery and vehicles industry
- Household appliances
- Wearable equipments

The series of products are accord with standards of RoHS and HALOGEN.

STORAGE CONDITIONS: Storage in the darkness

STORAGE TEMPERATURE: $\leq 30\text{ }^{\circ}\text{C}$

STORAGE HUMIDITY: $\leq 70\%$

The height of the stacking should not be more than 7 layers and the total height should not be more than 1m.

SHELF LIFE: Two years at storage conditions

Thermal gap filler has excellent flexibility insulation, compressibility and natural surface viscosity performances. It used to fill the gap and realize the heat transfer between the heating parts and cooling parts. It also has insulation and shock mitigation effects. Meanwhile, it can satisfy the design requirements for minitype and ultra-thin equipments with excellent manufacturability and practicability. With wide range of thickness, it is widely used in electronic products.

PROPERTIES

Items	Parameter	Unit	Test Method
Color	Light Yellow	-	Visual
Thickness	0.3~18	mm	ASTM D 374
Hardness	10~55(±5)	Shore C	ASTM D 2240
Density	2.93(±0.5)	g/cc	ASTM D 792
Tensile Strength	≥0.20	Mpa	ASTM D 412
Elongation	≥70	%	ASTM D 412
Compression Ratio	≥20(@50Psi)	%	ASTM D 575
UL Certification	V-0,5V	-	UL94
Operating Temperature	-50~200	°C	IEC 60068-2-14

THERMAL CHARACTERISTIC

Thermal Conductivity	2.5(±0.2)	W/m·K	ASTM D 5470
Thermal Resistance	≤1.0(@20Psi/1mm)	°Cin ² /W	ASTM D 5470

ELECTRICAL PROPERTIES

Breakdown Voltage	≥8(@1mm)	KV	ASTM D 149
Volume Resistivity	≥10 ⁸	Ω·cm	ASTM D 257

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APPLICATION METHOD:

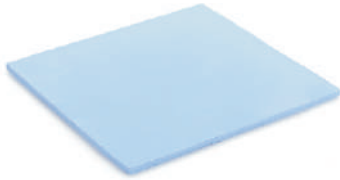
Thermal Gap Filler must be compressed to make up for device tolerances and to remove air from the interface when it is used, so our interface material can have good contact with both the heat dissipating component and the heat generating component. In general, there are three kinds of compression for the interface material:

1. When the hardness is less than Shore C 20, it is recommended to use 30% to 40% of the compression.
2. When the hardness between Shore C 20 to Shore C 40, it is recommended to use 25% to 30% of the compression.
3. When the hardness is more than Shore C 40, it is recommended to use 20% of the compression.

HFC H300 series

【 Thermal Gap Filler 】

DATA SHEET



- Product picture -

FEATURES:

- Soft, excellent compression performance
- Low thermal resistance
- Being recognized as UL94 V-0
- Viscous surface
- Being able to work under low pressure
- Excellent insulation performance and thermal resistance

APPLICATIONS:

- Between chip and heat-dissipation modules
- Optoelectronic Industry
- Netcom products
- New energy battery and vehicles industry
- Household appliances
- Wearable equipments

The series of products are accord with standards of RoHS and HALOGEN.

STORAGE CONDITIONS: Storage in the darkness

STORAGE TEMPERATURE: $\leq 30\text{ }^{\circ}\text{C}$

STORAGE HUMIDITY: $\leq 70\%$

The height of the stacking should not be more than 7 layers and the total height should not be more than 1m.

SHELF LIFE: Two years at storage conditions

Thermal gap filler has excellent flexibility insulation, compressibility and natural surface viscosity performances. It is used to fill the gap and realize the heat transfer between the heating parts and cooling parts. It also has insulation and shock mitigation effects. Meanwhile, it can satisfy the design requirements for minitype and ultra-thin equipments with excellent manufacturability and practicability. With wide range of thickness, it is widely used in electronic products.

PROPERTIES

Items	Parameter	Unit	Test Instrument
Color	Sky Blue	-	Visual
Thickness	0.3~18	mm	ASTM D 374
Hardness	15~55(±5)	Shore C	ASTM D 2240
Density	2.95(±0.5)	g/cc	ASTM D 792
Tensile Strength	≥ 0.15	Mpa	ASTM D 412
Elongation	≥ 60	%	ASTM D 412
Compression Ratio	≥ 20 (@50Psi)	%	ASTM D 575
UL Certification	V-0,5V	-	UL94
Operating Temperature	-50~180	$^{\circ}\text{C}$	IEC 60068-2-14

THERMAL CHARACTERISTIC

Thermal Conductivity	3.0(±0.25)	W/m·K	ASTM D 5470
Thermal Resistance	≤ 0.9 (@20Psi/1mm)	$^{\circ}\text{Cin}^2/\text{W}$	ASTM D 5470

ELECTRICAL PROPERTIES

Breakdown Voltage	≥ 8 (@1mm)	KV	ASTM D 149
Volume Resistivity	$\geq 10^8$	$\Omega\text{-cm}$	ASTM D 257

All above data are copyrighted and elaborated by HFC

APPLICATION METHOD:

Thermal Gap Filler must be compressed to make up for device tolerances and to remove air from the interface when it is used, so our interface material can have good contact with both the heat dissipating component and the heat generating component. In general, there are three kinds of compression for the interface material:

1. When the hardness is less than Shore C 20, it is recommended to use 30% to 40% of the compression.
2. When the hardness between Shore C 20 to Shore C 40, it is recommended to use 25% to 30% of the compression.
3. When the hardness is more than Shore C 40, it is recommended to use 20% of the compression.

HFC H300-DR series

【 Thermal Gap Filler 】

DATA SHEET



- Product picture -

FEATURES:

- Soft, excellent compression performance
- Low thermal resistance
- Being recognized as UL94 V-0
- Viscous surface
- Being able to work under low pressure
- Excellent insulation performance and thermal resistance

APPLICATIONS:

- Between chip and heat-dissipation modules
- Optoelectronic Industry
- Netcom products
- New energy battery and vehicles industry
- Household appliances
- Wearable equipments

The series of products are accord with standards of RoHS and HALOGEN.

STORAGE CONDITIONS: Storage in the darkness

STORAGE TEMPERATURE: $\leq 30\text{ }^{\circ}\text{C}$

STORAGE HUMIDITY: $\leq 70\%$

The height of the stacking should not be more than 7 layers and the total height should not be more than 1m.

SHELF LIFE: Two years at storage conditions

Thermal gap filler has excellent flexibility insulation, compressibility and natural surface viscosity performances. It used to fill the gap and realize the heat transfer between the heating parts and cooling parts. It also has insulation and shock mitigation effects. Meanwhile, it can satisfy the design requirements for minitype and ultra-thin equipments with excellent manufacturability and practicability. With wide range of thickness, it is widely used in electronic products.

PROPERTIES

Items	Parameter	Unit	Test Instrument
Color	White	-	Visual
Thickness	0.5~2	mm	ASTM D 374
Hardness	20-40(± 5)	Shore C	ASTM D 2240
Density	2.95(± 0.5)	g/cc	ASTM D 792
Tensile Strength	≥ 0.12	Mpa	ASTM D 412
Elongation	≥ 100	%	ASTM D 412
Compression Ratio	≥ 30 (@50Psi)	%	ASTM D 575
Operating Temperature	-50~180	$^{\circ}\text{C}$	IEC 60068-2-14

THERMAL CHARACTERISTIC

Thermal Conductivity	3.0(± 0.2)	W/m·K	ASTM D 5470
Thermal Resistance	≤ 0.9 (@20Psi/1mm)	$^{\circ}\text{Cin}^2/\text{W}$	ASTM D 5470

ELECTRICAL PROPERTIES

Breakdown Voltage	≥ 8 (@1mm)	KV	ASTM D 149
Volume Resistivity	$\geq 10^8$	$\Omega\text{-cm}$	ASTM D 257

All above data are copyrighted and elaborated by HFC

APPLICATION METHOD:

Thermal Gap Filler must be compressed to make up for device tolerances and to remove air from the interface when it is used, so our interface material can have good contact with both the heat dissipating component and the heat generating component. In general, there are three kinds of compression for the interface material:

1. When the hardness is less than Shore C 20, it is recommended to use 30% to 40% of the compression.
2. When the hardness between Shore C 20 to Shore C 40, it is recommended to use 25% to 30% of the compression.
3. When the hardness is more than Shore C 40, it is recommended to use 20% of the compression.

HFC H300-R8 series

【 Thermal Gap Filler 】

DATA SHEET



- Product picture -

FEATURES:

- Soft, excellent compression performance
- Low thermal resistance
- Being recognized as UL94 V-0
- Viscous surface
- Being able to work under low pressure
- Excellent insulation performance and thermal resistance

APPLICATIONS:

- Between chip and heat-dissipation modules
- Optoelectronic Industry
- Netcom products
- New energy battery and vehicles industry
- Household appliances
- Wearable equipments

The series of products are accord with standards of RoHS and HALOGEN.

STORAGE CONDITIONS: Storage in the darkness

STORAGE TEMPERATURE: $\leq 30\text{ }^{\circ}\text{C}$

STORAGE HUMIDITY: $\leq 70\%$

The height of the stacking should not be more than 7 layers and the total height should not be more than 1m.

SHELF LIFE: Two years at storage conditions

APPLICATION METHOD:

Thermal Gap Filler must be compressed to make up for device tolerances and to remove air from the interface when it is used, so our interface material can has good contact with both the heat dissipating component and the heat generating component. In general, there are three kinds of compression for the interface material:

1. When the hardness is less than Shore C 20, it is recommended to use 30% to 40% of the compression.
2. When the hardness between Shore C 20 to Shore C 40, it is recommended to use 25% to 30% of the compression.
3. When the hardness is more than Shore C 40, it is recommended to use 20% of the compression.

The material has a very low dielectric constant to ensure that the delay time in signal transmission is short enough instead of hindering signal transmission,so as to ensure signal reception and transmission smoothly.It is widely used in network communication equipemt.

PROPERTIES

Items	Parameter	Unit	Test Instrument
Color	White	-	Visual
Thickness	1~4	mm	ASTM D 374
Hardness	35~50(± 5)	Shore C	ASTM D 2240
Density	1.5(± 0.5)	g/cc	ASTM D 792
Tensile Strength	≥ 0.15	Mpa	ASTM D 412
Compression Ratio	≥ 20 (@50Psi)	%	ASTM D 575
UL Certification	V-0	-	UL94
Operating Temperature	-50~160	$^{\circ}\text{C}$	IEC 60068-2-14

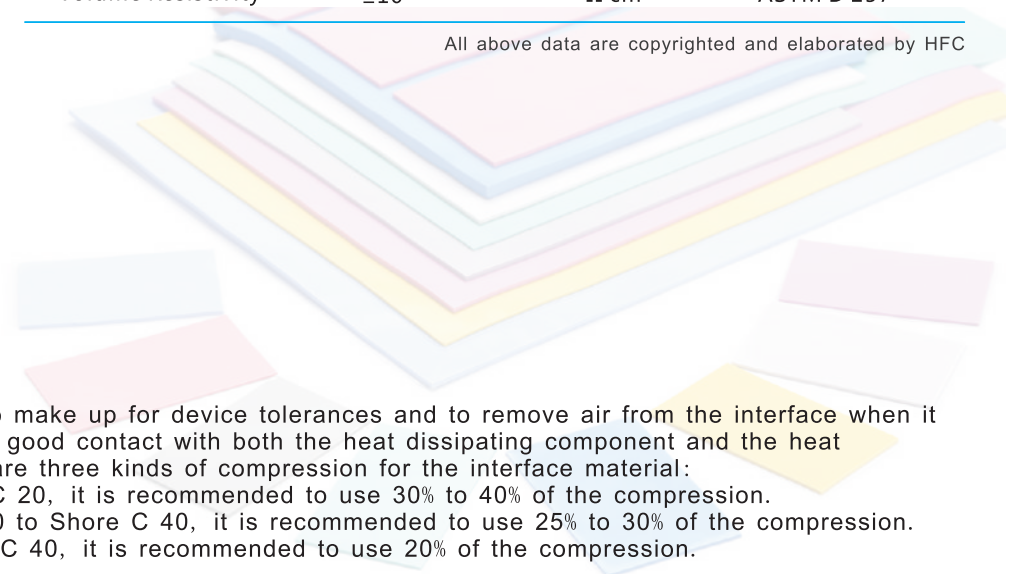
THERMAL CHARACTERISTIC

Thermal Conductivity	3.0(± 0.5)	W/m·K	ASTM D 5470
Thermal Resistance	≤ 1.2 (@20Psi/1mm)	$^{\circ}\text{Cin}^2/\text{W}$	ASTM D 5470

ELECTRICAL PROPERTIES

Breakdown Voltage	≥ 10 (@1mm)	KV	ASTM D 149
Volume Resistivity	$\geq 10^{10}$	$\Omega\cdot\text{cm}$	ASTM D 257

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HFC H300-Soft series

【 Thermal Gap Filler 】

DATA SHEET



- Product picture -

FEATURES:

- Ultra-soft, excellent compression performance
- Low thermal resistance
- Being recognized as UL94 V-0
- Viscous surface
- Being able to work under low pressure
- Excellent insulation performance and

APPLICATIONS:

- Between chip and heat-dissipation modules
- Optoelectronic Industry
- Netcom products
- New energy battery and vehicles industry
- Household appliances
- Wearable equipments

The series of products are accord with standards of RoHS and HALOGEN.

STORAGE CONDITIONS: Storage in the darkness

STORAGE TEMPERATURE: $\leq 30\text{ }^{\circ}\text{C}$

STORAGE HUMIDITY: $\leq 70\%$

The height of the stacking should not be more than 7 layers and the total height should not be more than 1m.

SHELF LIFE: Two years at storage conditions

Thermal gap filler has excellent flexibility insulation, compressibility and natural surface viscosity performances. It used to fill the gap and realize the heat transfer between the heating parts and cooling parts. It also has insulation and shock mitigation effects. Meanwhile, it can satisfy the design requirements for minitype and ultra-thin equipments with excellent manufacturability and practicability. With wide range of thickness, it is widely used in electronic products.

PROPERTIES

Items	Parameter	Unit	Test Instrument
Color	Sky Blue	-	Visual
Thickness	1~4	mm	ASTM D 374
Hardness	20(± 5)	Shore C	ASTM D 2240
Density	3.05(± 0.5)	g/cc	ASTM D 792
Tensile Strength	≥ 0.15	Mpa	ASTM D 412
Elongation	≥ 60	%	ASTM D 412
Compression Ratio	≥ 40 (@50Psi)	%	ASTM D 575
UL Certification	V-0,5V	-	UL94
Operating Temperature	-50~180	$^{\circ}\text{C}$	IEC 60068-2-14

THERMAL CHARACTERISTIC

Thermal Conductivity	3.0(± 0.25)	W/m·K	ASTM D 5470
Thermal Resistance	≤ 0.7 (@20Psi/1mm)	$^{\circ}\text{Cin}^2/\text{W}$	ASTM D 5470

ELECTRICAL PROPERTIES

Breakdown Voltage	≥ 8 (@1mm)	KV	ASTM D 149
Volume Resistivity	$\geq 10^8$	$\Omega\text{-cm}$	ASTM D 257

All above data are copyrighted and elaborated by HFC

APPLICATION METHOD:

Thermal Gap Filler must be compressed to make up for device tolerances and to remove air from the interface when it is used, so our interface material can have good contact with both the heat dissipating component and the heat generating component. In general, there are three kinds of compression for the interface material:

1. When the hardness is less than Shore C 20, it is recommended to use 30% to 40% of the compression.
2. When the hardness between Shore C 20 to Shore C 40, it is recommended to use 25% to 30% of the compression.
3. When the hardness is more than Shore C 40, it is recommended to use 20% of the compression.

HFC H350 series

【 Thermal Gap Filler 】

DATA SHEET



- Product picture -

FEATURES:

- Soft, excellent compression performance
- Low thermal resistance
- Being recognized as UL94 V-0
- Viscous surface
- Being able to work under low pressure
- Excellent insulation performance and thermal resistance

APPLICATIONS:

- Between chip and heat-dissipation modules
- Optoelectronic Industry
- Netcom products
- New energy battery and vehicles industry
- Household appliances
- Wearable equipments

The series of products are accord with standards of RoHS and HALOGEN.

STORAGE CONDITIONS: Storage in the darkness

STORAGE TEMPERATURE: $\leq 30\text{ }^{\circ}\text{C}$

STORAGE HUMIDITY: $\leq 70\%$

The height of the stacking should not be more than 7 layers and the total height should not be more than 1m.

SHELF LIFE: Two years at storage conditions

Thermal gap filler has excellent flexibility insulation, compressibility and natural surface viscosity performances. It used to fill the gap and realize the heat transfer between the heating parts and cooling parts. It also has insulation and shock mitigation effects. Meanwhile, it can satisfy the design requirements for minitype and ultra-thin equipments with excellent manufacturability and practicability. With wide range of thickness, it is widely used in electronic products.

PROPERTIES

Items	Parameter	Unit	Test Instrument
Color	Green	-	Visual
Thickness	0.5~3	mm	ASTM D 374
Hardness	18~60(±5)	Shore C	ASTM D 2240
Density	3.05(±0.5)	g/cc	ASTM D 792
Tensile Strength	≥ 0.15	Mpa	ASTM D 412
Elongation	≥ 60	%	ASTM D 412
Compression Ratio	≥ 15 (@50Psi)	%	ASTM D 575
UL Certification	V-0,5V	-	UL94
Operating Temperature	-50~180	$^{\circ}\text{C}$	IEC 60068-2-14

THERMAL CHARACTERISTIC

Thermal Conductivity	3.5(±0.25)	W/m·K	ASTM D 5470
Thermal Resistance	≤ 0.8 (@20Psi/1mm)	$^{\circ}\text{Cin}^2/\text{W}$	ASTM D 5470

ELECTRICAL PROPERTIES

Breakdown Voltage	≥ 8 (@1mm)	KV	ASTM D 149
Volume Resistivity	$\geq 10^8$	$\Omega\text{-cm}$	ASTM D 257

All above data are copyrighted and elaborated by HFC

APPLICATION METHOD:

Thermal Gap Filler must be compressed to make up for device tolerances and to remove air from the interface when it is used, so our interface material can have good contact with both the heat dissipating component and the heat generating component. In general, there are three kinds of compression for the interface material:

1. When the hardness is less than Shore C 20, it is recommended to use 30% to 40% of the compression.
2. When the hardness between Shore C 20 to Shore C 40, it is recommended to use 25% to 30% of the compression.
3. When the hardness is more than Shore C 40, it is recommended to use 20% of the compression.

HFC H350-Soft series

【 Thermal Gap Filler 】

DATA SHEET



- Product picture -

FEATURES:

- Ultra-soft, excellent compression performance
- Low thermal resistance
- Being recognized as UL94 V-0
- Viscous surface
- Being able to work under low pressure
- Excellent insulation performance and

APPLICATIONS:

- Between chip and heat-dissipation modules
- Optoelectronic Industry
- Netcom products
- New energy battery and vehicles industry
- Household appliances
- Wearable equipments

The series of products are accord with standards of RoHS and HALOGEN.

STORAGE CONDITIONS: Storage in the darkness

STORAGE TEMPERATURE: $\leq 30\text{ }^{\circ}\text{C}$

STORAGE HUMIDITY: $\leq 70\%$

The height of the stacking should not be more than 7 layers and the total height should not be more than 1m.

SHELF LIFE: Two years at storage conditions

Thermal gap filler has excellent flexibility insulation, compressibility and natural surface viscosity performances. It used to fill the gap and realize the heat transfer between the heating parts and cooling parts. It also has insulation and shock mitigation effects. Meanwhile, it can satisfy the design requirements for minitype and ultra-thin equipments with excellent manufacturability and practicability. With wide range of thickness, it is widely used in electronic products.

PROPERTIES

Items	Parameter	Unit	Test Instrument
Color	Green	-	Visual
Thickness	1~4	mm	ASTM D 374
Hardness	25(±5)	Shore 00	ASTM D 2240
Density	3.05(±0.5)	g/cc	ASTM D 792
Tensile Strength	≥ 0.15	Mpa	ASTM D 412
Elongation	≥ 60	%	ASTM D 412
Compression Ratio	≥ 40 (@50Psi)	%	ASTM D 575
UL Certification	V-0,5V	-	UL94
Operating Temperature	-50~180	$^{\circ}\text{C}$	IEC 60068-2-14

THERMAL CHARACTERISTIC

Thermal Conductivity	3.5(±0.25)	W/m·K	ASTM D 5470
Thermal Resistance	≤ 0.7 (@20Psi/1mm)	$^{\circ}\text{Cin}^2/\text{W}$	ASTM D 5470

ELECTRICAL PROPERTIES

Breakdown Voltage	≥ 8	KV	ASTM D 149
Volume Resistivity	$\geq 10^8$	$\Omega\text{-cm}$	ASTM D 257

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APPLICATION METHOD:

Thermal Gap Filler must be compressed to make up for device tolerances and to remove air from the interface when it is used, so our interface material can have good contact with both the heat dissipating component and the heat generating component. In general, there are three kinds of compression for the interface material:

1. When the hardness is less than Shore C 20, it is recommended to use 30% to 40% of the compression.
2. When the hardness between Shore C 20 to Shore C 40, it is recommended to use 25% to 30% of the compression.
3. When the hardness is more than Shore C 40, it is recommended to use 20% of the compression.

HFC H400 series

【 Thermal Gap Filler 】

DATA SHEET



- Product picture -

FEATURES:

- Soft, excellent compression performance
- Low thermal resistance
- Being recognized as UL94 V-0
- Viscous surface
- Being able to work under low pressure
- Excellent insulation performance and thermal resistance

APPLICATIONS:

- Between chip and heat-dissipation modules
- Optoelectronic Industry
- Netcom products
- New energy battery and vehicles industry
- Household appliances
- Wearable equipments

The series of products are accord with standards of RoHS and HALOGEN.

STORAGE CONDITIONS: Storage in the darkness

STORAGE TEMPERATURE: $\leq 30\text{ }^{\circ}\text{C}$

STORAGE HUMIDITY: $\leq 70\%$

The height of the stacking should not be more than 7 layers and the total height should not be more than 1m.

SHELF LIFE: Two years at storage conditions

Thermal gap filler has excellent flexibility insulation, compressibility and natural surface viscosity performances. It used to fill the gap and realize the heat transfer between the heating parts and cooling parts. It also has insulation and shock mitigation effects. Meanwhile, it can satisfy the design requirements for minitype and ultra-thin equipments with excellent manufacturability and practicability. With wide range of thickness, it is widely used in electronic products.

PROPERTIES

Items	Parameter	Unit	Test Instrument
Color	Purple	-	Visual
Thickness	0.5~4	mm	ASTM D 374
Hardness	35~55(±5)	Shore C	ASTM D 2240
Density	3.12(±0.5)	g/cc	ASTM D 792
Tensile Strength	≥ 0.15	Mpa	ASTM D 412
Elongation	≥ 60	%	ASTM D 412
Compression Ratio	≥ 15 (@50Psi)	%	ASTM D 575
UL Certification	V-0,5V	-	UL94
Operating Temperature	-50~180	$^{\circ}\text{C}$	IEC 60068-2-14

THERMAL CHARACTERISTIC

Thermal Conductivity	4.0(±0.25)	W/m·K	ASTM D 5470
Thermal Resistance	≤ 0.75 (@20Psi/1mm)	$^{\circ}\text{Cin}^2/\text{W}$	ASTM D 5470

ELECTRICAL PROPERTIES

Breakdown Voltage	≥ 8 (@1mm)	KV	ASTM D 149
Volume Resistivity	$\geq 10^8$	$\Omega\text{-cm}$	ASTM D 257

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APPLICATION METHOD:

Thermal Gap Filler must be compressed to make up for device tolerances and to remove air from the interface when it is used, so our interface material can have good contact with both the heat dissipating component and the heat generating component. In general, there are three kinds of compression for the interface material:

1. When the hardness is less than Shore C 20, it is recommended to use 30% to 40% of the compression.
2. When the hardness between Shore C 20 to Shore C 40, it is recommended to use 25% to 30% of the compression.
3. When the hardness is more than Shore C 40, it is recommended to use 20% of the compression.

HFC H500 series

【 Thermal Gap Filler 】

DATA SHEET



- Product picture -

FEATURES:

- Soft, excellent compression performance
- Low thermal resistance
- Being recognized as UL94 V-0
- Viscous surface
- Being able to work under low pressure
- Excellent insulation performance and thermal resistance

APPLICATIONS:

- Between chip and heat-dissipation modules
- Optoelectronic Industry
- Netcom products
- New energy battery and vehicles industry
- Household appliances
- Wearable equipments

The series of products are accord with standards of RoHS and HALOGEN.

STORAGE CONDITIONS: Storage in the darkness

STORAGE TEMPERATURE: $\leq 30\text{ }^{\circ}\text{C}$

STORAGE HUMIDITY: $\leq 70\%$

The height of the stacking should not be more than 7 layers and the total height should not be more than 1m.

SHELF LIFE: Two years at storage conditions

Thermal gap filler has excellent flexibility insulation, compressibility and natural surface viscosity performances. It used to fill the gap and realize the heat transfer between the heating parts and cooling parts. It also has insulation and shock mitigation effects. Meanwhile, it can satisfy the design requirements for minitype and ultra-thin equipments with excellent manufacturability and practicability. With wide range of thickness, it is widely used in electronic products.

PROPERTIES

Items	Parameter	Unit	Test Instrument
Color	White	-	Visual
Thickness	0.5~3	mm	ASTM D 374
Hardness	35~50(± 5)	Shore C	ASTM D 2240
Density	3.2(± 0.5)	g/cc	ASTM D 792
Tensile Strength	≥ 0.15	Mpa	ASTM D 412
Elongation	≥ 60	%	ASTM D 412
Compression Ratio	≥ 15 (@50Psi)	%	ASTM D 575
Operating Temperature	-50~150	$^{\circ}\text{C}$	IEC 60068-2-14

THERMAL CHARACTERISTIC

Thermal Conductivity	5.0(± 0.5)	W/m·K	ASTM D 5470
Thermal Resistance	≤ 0.7 (@20Psi/1mm)	$^{\circ}\text{Cin}^2/\text{W}$	ASTM D 5470

ELECTRICAL PROPERTIES

Breakdown Voltage	≥ 7 (@1mm)	KV	ASTM D 149
Volume Resistivity	$\geq 10^8$	$\Omega\text{-cm}$	ASTM D 257

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APPLICATION METHOD:

Thermal Gap Filler must be compressed to make up for device tolerances and to remove air from the interface when it is used, so our interface material can have good contact with both the heat dissipating component and the heat generating component. In general, there are three kinds of compression for the interface material:

1. When the hardness is less than Shore C 20, it is recommended to use 30% to 40% of the compression.
2. When the hardness between Shore C 20 to Shore C 40, it is recommended to use 25% to 30% of the compression.
3. When the hardness is more than Shore C 40, it is recommended to use 20% of the compression.

HFC H500R series

【 Thermal Gap Filler 】

DATA SHEET



- Product picture -

FEATURES:

- Soft, excellent compression performance
- Low thermal resistance
- Being recognized as UL94 V-0
- Viscous surface
- Being able to work under low pressure
- Excellent insulation performance and thermal resistance

APPLICATIONS:

- Between chip and heat-dissipation modules
- Optoelectronic Industry
- Netcom products
- New energy battery and vehicles industry
- Household appliances
- Wearable equipments

The series of products are accord with standards of RoHS and HALOGEN.

STORAGE CONDITIONS: Storage in the darkness

STORAGE TEMPERATURE: $\leq 30\text{ }^{\circ}\text{C}$

STORAGE HUMIDITY: $\leq 70\%$

The height of the stacking should not be more than 7 layers and the total height should not be more than 1m.

SHELF LIFE: Two years at storage conditions

Thermal gap filler has excellent flexibility insulation, compressibility and natural surface viscosity performances. It used to fill the gap and realize the heat transfer between the heating parts and cooling parts. It also has insulation and shock mitigation effects. Meanwhile, it can satisfy the design requirements for minitype and ultra-thin equipments with excellent manufacturability and practicability. With wide range of thickness, it is widely used in electronic products.

PROPERTIES

Items	Parameter	Unit	Test Instrument
Color	Gray	-	Visual
Thickness	0.5~3	mm	ASTM D 374
Hardness	35~50(± 5)	Shore C	ASTM D 2240
Density	3.1(± 0.5)	g/cc	ASTM D 792
Tensile Strength	≥ 0.15	Mpa	ASTM D 412
Elongation	≥ 60	%	ASTM D 412
Compression Ratio	≥ 15 (@50Psi)	%	ASTM D 575
Operating Temperature	-50~150	$^{\circ}\text{C}$	IEC 60068-2-14

THERMAL CHARACTERISTIC

Thermal Conductivity	5.0(± 0.5)	W/m·K	ASTM D 5470
Thermal Resistance	≤ 0.6 (@20Psi/1mm)	$^{\circ}\text{Cin}^2/\text{W}$	ASTM D 5470

ELECTRICAL PROPERTIES

Breakdown Voltage	≥ 3 (@1mm)	KV	ASTM D 149
Volume Resistivity	$\geq 10^8$	$\Omega\text{-cm}$	ASTM D 257

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APPLICATION METHOD:

Thermal Gap Filler must be compressed to make up for device tolerances and to remove air from the interface when it is used, so our interface material can have good contact with both the heat dissipating component and the heat generating component. In general, there are three kinds of compression for the interface material:

1. When the hardness is less than Shore C 20, it is recommended to use 30% to 40% of the compression.
2. When the hardness between Shore C 20 to Shore C 40, it is recommended to use 25% to 30% of the compression.
3. When the hardness is more than Shore C 40, it is recommended to use 20% of the compression.

HFC H500-R8 series

【 Thermal Gap Filler 】

DATA SHEET



- Product picture -

FEATURES:

- Low thermal resistance
- Being recognized as UL94 V-0
- Viscous surface
- Being able to work under low pressure
- Excellent insulation performance and thermal resistance

APPLICATIONS:

- Between chip and heat-dissipation modules
- Optoelectronic Industry
- Netcom products
- New energy battery and vehicles industry
- Household appliances
- Wearable equipments

The series of products are accord with standards of RoHS and HALOGEN.

STORAGE CONDITIONS: Storage in the darkness

STORAGE TEMPERATURE: $\leq 30\text{ }^{\circ}\text{C}$

STORAGE HUMIDITY: $\leq 70\%$

The height of the stacking should not be more than 7 layers and the total height should not be more than 1m.

SHELF LIFE: Two years at storage conditions

Thermal gap filler has excellent flexibility insulation, compressibility and natural surface viscosity performances. It used to fill the gap and realize the heat transfer between the heating parts and cooling parts. It also has insulation and shock mitigation effects. Meanwhile, it can satisfy the design requirements for minitype and ultra-thin equipments with excellent manufacturability and practicability. With wide range of thickness, it is widely used in electronic products.

PROPERTIES

Items	Parameter	Unit	Test Instrument
Color	Dark Gray	-	Visual
Thickness	1~4	mm	ASTM D 374
Hardness	35~50(± 5)	Shore C	ASTM D 2240
Density	2.0(± 0.5)	g/cc	ASTM D 792
Tensile Strength	≥ 0.15	Mpa	ASTM D 412
Elongation	≥ 60	%	ASTM D 412
Compression Ratio	≥ 20 (@50Psi)	%	ASTM D 575
UL Certification	V-0	-	UL94
Operating Temperature	-50~160	$^{\circ}\text{C}$	IEC 60068-2-14

THERMAL CHARACTERISTIC

Thermal Conductivity	5.0(± 0.5)	W/m·K	ASTM D 5470
Thermal Resistance	≤ 0.6 (@20Psi/1mm)	$^{\circ}\text{Cin}^2/\text{W}$	ASTM D 5470

ELECTRICAL PROPERTIES

Volume Resistivity	$\geq 10^{10}$	$\Omega\text{-cm}$	ASTM D 257
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APPLICATION METHOD:

Thermal Gap Filler must be compressed to make up for device tolerances and to remove air from the interface when it is used, so our interface material can have good contact with both the heat dissipating component and the heat generating component. In general, there are three kinds of compression for the interface material:

1. When the hardness is less than Shore C 20, it is recommended to use 30% to 40% of the compression.
2. When the hardness between Shore C 20 to Shore C 40, it is recommended to use 25% to 30% of the compression.
3. When the hardness is more than Shore C 40, it is recommended to use 20% of the compression.

HFC H600 series

【 Thermal Gap Filler 】

DATA SHEET



- Product picture -

FEATURES:

- Low thermal resistance
- Being recognized as UL94 V-0
- Viscous surface
- Being able to work under low pressure
- Excellent insulation performance and thermal resistance

APPLICATIONS:

- Between chip and heat-dissipation modules
- Optoelectronic Industry
- Netcom products
- New energy battery and vehicles industry
- Household appliances
- Wearable equipments

The series of products are accord with standards of RoHS and HALOGEN.

STORAGE CONDITIONS: Storage in the darkness

STORAGE TEMPERATURE: $\leq 30\text{ }^{\circ}\text{C}$

STORAGE HUMIDITY: $\leq 70\%$

The height of the stacking should not be more than 7 layers and the total height should not be more than 1m.

SHELF LIFE: Two years at storage conditions

Thermal gap filler has excellent flexibility insulation, compressibility and natural surface viscosity performances. It used to fill the gap and realize the heat transfer between the heating parts and cooling parts. It also has insulation and shock mitigation effects. Meanwhile, it can satisfy the design requirements for minitype and ultra-thin equipments with excellent manufacturability and practicability. With wide range of thickness, it is widely used in electronic products.

PROPERTIES

Items	Parameter	Unit	Test Instrument
Color	Gray	-	Visual
Thickness	0.5~3	mm	ASTM D 374
Hardness	35~50(± 5)	Shore C	ASTM D 2240
Density	3.2(± 0.5)	g/cc	ASTM D 792
Tensile Strength	≥ 0.15	Mpa	ASTM D 412
Elongation	≥ 50	%	ASTM D 412
Compression Ratio	≥ 15 (@50Psi)	%	ASTM D 575
Operating Temperature	-50~150	$^{\circ}\text{C}$	IEC 60068-2-14

THERMAL CHARACTERISTIC

Thermal Conductivity	6.0(± 0.5)	W/m·K	ASTM D 5470
Thermal Resistance	≤ 0.5 (@20Psi/1mm)	$^{\circ}\text{Cin}^2/\text{W}$	ASTM D 5470

ELECTRICAL PROPERTIES

Breakdown Voltage	≥ 3 (@1mm)	KV	ASTM D 149
Volume Resistivity	$\geq 10^8$	$\Omega\text{-cm}$	ASTM D 257

All above data are copyrighted and elaborated by HFC

APPLICATION METHOD:

Thermal Gap Filler must be compressed to make up for device tolerances and to remove air from the interface when it is used, so our interface material can have good contact with both the heat dissipating component and the heat generating component. In general, there are three kinds of compression for the interface material:

1. When the hardness is less than Shore C 20, it is recommended to use 30% to 40% of the compression.
2. When the hardness between Shore C 20 to Shore C 40, it is recommended to use 25% to 30% of the compression.
3. When the hardness is more than Shore C 40, it is recommended to use 20% of the compression.

HFC H700 series

【 Thermal Gap Filler 】

DATA SHEET



- Product picture -

FEATURES:

- Low thermal resistance
- Being recognized as UL94 V-0
- Viscous surface
- Being able to work under low pressure
- Excellent insulation performance and thermal resistance

APPLICATIONS:

- Between chip and heat-dissipation modules
- Optoelectronic Industry
- Netcom products
- New energy battery and vehicles industry
- Household appliances
- Wearable equipments

The series of products are accord with standards of RoHS and HALOGEN.

STORAGE CONDITIONS: Storage in the darkness

STORAGE TEMPERATURE: $\leq 30\text{ }^{\circ}\text{C}$

STORAGE HUMIDITY: $\leq 70\%$

The height of the stacking should not be more than 7 layers and the total height should not be more than 1m.

SHELF LIFE: Two years at storage conditions

Thermal gap filler has excellent flexibility insulation, compressibility and natural surface viscosity performances. It is used to fill the gap and realize the heat transfer between the heating parts and cooling parts. It also has insulation and shock mitigation effects. Meanwhile, it can satisfy the design requirements for minitype and ultra-thin equipments with excellent manufacturability and practicability. With wide range of thickness, it is widely used in electronic products.

PROPERTIES

Items	Parameter	Unit	Test Instrument
Color	Gray	-	Visual
Thickness	0.5~3	mm	ASTM D 374
Hardness	35(± 5)	Shore C	ASTM D 2240
Density	3.2(± 0.5)	g/cc	ASTM D 792
Tensile Strength	≥ 0.1	Mpa	ASTM D 412
Elongation	≥ 45	%	ASTM D 412
Compression Ratio	≥ 15 (@50Psi)	%	ASTM D 575
Operating Temperature	-50~150	$^{\circ}\text{C}$	IEC 60068-2-14

THERMAL CHARACTERISTIC

Thermal Conductivity	7.0(± 0.5)	W/m·K	ASTM D 5470
Thermal Resistance	≤ 0.3 (@20Psi/1mm)	$^{\circ}\text{Cin}^2/\text{W}$	ASTM D 5470

ELECTRICAL PROPERTIES

Breakdown Voltage	≥ 2 (@1mm)	KV	ASTM D 149
Volume Resistivity	$\geq 10^8$	$\Omega\text{-cm}$	ASTM D 257

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APPLICATION METHOD:

Thermal Gap Filler must be compressed to make up for device tolerances and to remove air from the interface when it is used, so our interface material can have good contact with both the heat dissipating component and the heat generating component. In general, there are three kinds of compression for the interface material:

1. When the hardness is less than Shore C 20, it is recommended to use 30% to 40% of the compression.
2. When the hardness between Shore C 20 to Shore C 40, it is recommended to use 25% to 30% of the compression.
3. When the hardness is more than Shore C 40, it is recommended to use 20% of the compression.

HFC H700-Softseries

【 Thermal Gap Filler 】

DATA SHEET



- Product picture -

FEATURES:

- Being able to work under low pressure and excellent compression performance
- No rebound stress or low rebound stress
- Low thermal resistance
- Good interface contact
- Excellent insulation performance and high breakdown voltage
- Single adhesive

APPLICATIONS:

- Between chip and heat-dissipation modules
- Optoelectronic Industry
- Netcom products
- Household appliances
- Wearable equipments
- Assembly pressure sensitive environment

The series of products are accord with standards of RoHS and HALOGEN.

STORAGE CONDITIONS: Storage in the darkness

STORAGE TEMPERATURE: $\leq 30\text{ }^{\circ}\text{C}$

STORAGE HUMIDITY: $\leq 70\%$

The height of the stacking should not be more than 7 layers and the total height should not be more than 1m.

SHELF LIFE: Two years at storage conditions

HFC H700-soft thermal conductive silicon pad is a kind of thermal interface material with high thermal conductivity, low thermal resistance and single-surface. The product has good stress response and ultra-low installation stress, which can avoid the damage of installation stress to the parts such as chip, PCB and so on. The product has natural viscosity and high compressibility, which can fill the gap well and realize heat transfer between heating parts and cooling parts. It is an excellent heat conducting filler and is widely used in electronic products.

PROPERTIES

Items	Parameter	Unit	Test Instrument
Color	Gray	-	Visual
Thickness	1~4	mm	ASTM D 374
Hardness	40(±5)	Shore 00	ASTM D 2240
Density	3.2(±0.2)	g/cc	ASTM D 792
Tensile Strength	≥ 0.05	Mpa	ASTM D 412
Elongation	≥ 40	%	ASTM D 412
Compression Ratio	≥ 50 (@50Psi)	%	ASTM D 575
UL Certification	V-0	-	UL94
Operating Temperature	-50~180	$^{\circ}\text{C}$	IEC 60068-2-14

THERMAL CHARACTERISTIC

Thermal Conductivity	7.0(±0.7)	W/m·K	ASTM D 5470
	@15Psi/2mm 0.28	$^{\circ}\text{Cin}^2/\text{W}$	ASTM D 5470
Thermal Resistance	@30Psi/2mm 0.22	$^{\circ}\text{Cin}^2/\text{W}$	ASTM D 5470
	@50Psi/2mm 0.15	$^{\circ}\text{Cin}^2/\text{W}$	ASTM D 5470

ELECTRICAL PROPERTIES

Breakdown Voltage	≥ 8 (@1mm)	KV	ASTM D 149
Volume Resistivity	$\geq 10^8$	$\Omega\text{-cm}$	ASTM D 257

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APPLICATION METHOD:

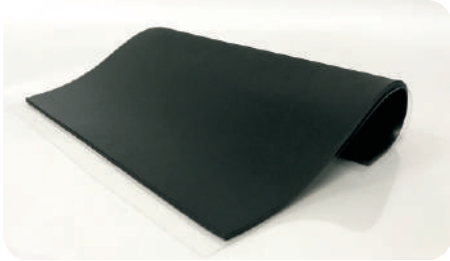
Thermal Gap Filler must be compressed to make up for device tolerances and to remove air from the interface when it is used, so our interface material can has good contact with both the heat dissipating component and the heat generating component. In general, there are three kinds of compression for the interface material:

1. When the hardness is less than Shore C 20, it is recommended to use 30% to 40% of the compression.
2. When the hardness between Shore C 20 to Shore C 40, it is recommended to use 25% to 30% of the compression.
3. When the hardness is more than Shore C 40, it is recommended to use 20% of the compression.

HFC H1500-R series

【 Thermal Gap Filler 】

DATA SHEET



- Product picture -

FEATURES:

- Soft, excellent compression performance
- Low thermal resistance
- Lightweight
- Being able to work under low pressure
- Excellent thermal stability property

APPLICATIONS:

- Military Industry
- Radar
- Large server
- GPU and image processor
- High frequency netcom equipment

The series of products are accord with standards of RoHS and HALOGEN.

STORAGE CONDITIONS: Storage in the darkness

STORAGE TEMPERATURE: $\leq 30\text{ }^{\circ}\text{C}$

STORAGE HUMIDITY: $\leq 70\%$

The height of the stacking should not be more than 7 layers and the total height should not be more than 1m.

SHELF LIFE: Two years at storage conditions

H1500-R is a new type of thermal pad with ultrahigh thermal conductivity and ultra-low thermal resistance. It is manufactured by an advanced arrangement technology that the high thermal conductivity fillers are uniformly and vertically aligned distributed in the polymer matrix, which can greatly increase the heat transfer efficiency. Meanwhile, the low filler loading also makes the material possess good mechanical properties and excellent thermal stability. It can be widely used in electronic fields with high requirement for heat dissipation, such as satellite, radar, large server, data processing center, mobile phone with high performance and so on.

PROPERTIES

Items	Parameter	Unit	Test Instrument
Color	Black	-	Visual
Thickness	0.5~2	mm	ASTM D 374
Hardness	45	Shore 00	ASTM D 2240
Density	1.3(± 0.2)	g/cc	ASTM D 792
UL Certification	V-0	-	UL94
Operating Temperature	-50~180	$^{\circ}\text{C}$	IEC 60068-2-14

THERMAL CHARACTERISTIC

Thermal Conductivity	15	W/m·K	ASTM D 5470
Thermal Resistance	≤ 0.15 (@20Psi/1mm)	$^{\circ}\text{Cin}^2/\text{W}$	ASTM D 5470

ELECTRICAL PROPERTIES

Breakdown Voltage	≥ 1.5 (@1mm)	KV	ASTM D 149
Volume Resistivity	$\geq 10^8$	$\Omega\text{-cm}$	ASTM D 257

All above data are copyrighted and elaborated by HFC

APPLICATION METHOD:

Thermal Gap Filler must be compressed to make up for device tolerances and to remove air from the interface when it is used, so our interface material can has good contact with both the heat dissipating component and the heat generating component. In general, there are three kinds of compression for the interface material:

1. When the hardness is less than Shore C 20, it is recommended to use 30% to 40% of the compression.
2. When the hardness between Shore C 20 to Shore C 40, it is recommended to use 25% to 30% of the compression.
3. When the hardness is more than Shore C 40, it is recommended to use 20% of the compression.

Silicone Free Thermal Pad series

【Thermal Gap filler】

DATA SHEET



- Product picture -

FEATURES:

- Without silicon components
- High thermal conductivity property
- Good flexibility, high strength and high elasticity

APPLICATIONS:

- Mobile electronic equipment
- Microprocessors and chips
- Automotive engine control unit
- Laptop
- Wireless communication hardware products

THICKNESS TOLERANCE(mm):

$0.5 < H < 1.0, \pm 0.1$
 $1.0 \leq H < 1.5, \pm 0.15$
 $1.5 \leq H < 2, \pm 0.2$
 $2 \leq H < 2.5, \pm 0.25$
 $H > 2.5, \pm 10\%$

The series of products are accord with standards of RoHS and HALOGEN.

Silicone Free Thermal Pad is a curing and molding material with of acrylic adhesive and thermal material. It has good insulating properties, excellent resistance to aging, high flexibility and good self-adhesive. Even after prolonged use it would not have oil leakage. Especially suitable for the silicone oil sensitive places, therefore they are widely used in high-end electronic industry such as high sensitivity detector and high-definition cameras.

PROPERTIES

Items	Parameter		Unit	Test Method
	H200SF	H300SF		
Color	Gray White	Gray White	-	Visual
Thickness	0.5~3	0.5~3	mm	ASTM D 374
Density	2.7(±0.5)	2.9(±0.5)	g/cc	ASTM D 792
Hardness	35~50(±5)	35~50(±5)	Shore C	ASTM D 2240
Initial Viscous	6(±1)	5(±1)	-	GB/T 4852-2002
Compression Ratio	≥25(@50Psi)	≥25(@50Psi)	%	ASTM D 575
Tensile Strength	≥0.15	≥0.15	Mpa	ASTM D 412
Elongation	≥80	≥80	%	ASTM D 412
Dielectric Constant	≥2(@1MHz)	≥2(@1MHz)	-	ASTM D 150
Dielectric Loss	≤0.1	≤0.1	-	ASTM D 150
Volatilation Matter	0.04	0.04	-	-
UL Certification	V0	V0	-	UL94
Operating Temperature	-40~150	-40~150	°C	IEC 60068-2-14

THERMAL CHARACTERISTIC

Thermal Conductivity	2.0(±0.2)	3.0(±0.25)	W/m·K	ASTM D 5470
Thermal Resistance	≤0.7(@20Psi/1mm)	≤0.6(@20Psi)	°Cin ² /W	ASTM D 5470

ELECTRICAL PROPERTIES

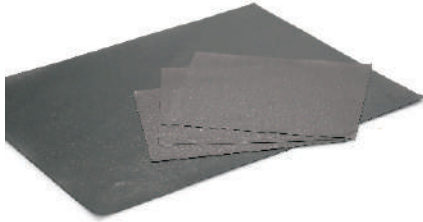
Breakdown Voltage	≥8(@1mm)	≥8(@1mm)	KV	ASTM D 149
Volume Resistivity	10 ⁸	10 ⁸	Ω.cm	ASTM D 257

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Thermal Absorbing Materials series

【Thermal Gap filler】

DATA SHEET



- Product picture -

APPLICATIONS:

- Communication equipments
- Optoelectronic Industry
- Netcom products
- High frequency module
- Soft circuit board

The series of products are accord with standards of RoHS and HALOGEN.

STORAGE CONDITIONS:Storage in the darkness

STORAGE TEMPERATURE: ≤ 30 °C

STORAGE HUMIDITY: ≤ 70%

SHELF LIFE: Two years at storage conditions

Thermal absorbing composite pad have both thermal conductivity and wave absorbing properties.It also has good elasticity and compressi-bility.When the requirements of anti-radiation of the chip itself or the requiriements being radiated are low,the composite material can simplify the whole module structure.

PROPERTIES

Items	Parameter			Unit	Test Method
	H100A15	H150A15	H200A15		
Color	Dark grey	Dark grey	Dark grey	-	Visual
Thickness	0.5~3	0.5~3	0.5~3	mm	ASTM D 374
Density	2.5±0.2	3.2±0.2	3.4±0.2	g/cc	ASTM D 792
Hardness	40~60(±5)	40~60(±5)	40~60(±5)	Shore C	ASTM D 2240
Compression Ratio	≥15(@50psi)	≥15(@50psi)	≥15(@50psi)	%	ASTM D 575
Tensile Strength	≥0.4	≥0.35	≥0.3	Mpa	ASTM D 412
Elongation	≥100	≥100	≥70	%	
Tear Strength	≥1.5	≥1.0	≥0.6	N/mm	ASTM D 624
Magnetic permeability	15±5	15±5	15±5	@1MHz	SJ 20512
Dielectric Constant	≥2	≥2	≥2	@1MHz	ASTM D 150
Dielectric loss	≤0.1	≤0.1	≤0.1	-	
Operating Temperature	-40~160	-40~160	-40~160	°C	IEC 60068-2-14

THERMAL CHARACTERISTIC

Thermal Conductivity	1±0.2	1.5±0.2	2.0±0.2	W/m·K	ASTM D 5470
Thermal Resistance	≤2.0	≤1.5	≤1.0	°Cin ² /W	ASTM D 5470

ELECTRICAL PROPERTIES

Breakdown Voltage	<0.1(@1mm)	<0.1(@1mm)	<0.1(@1mm)	KV	ASTM D 149
Volume Resistivity	≥10 ¹⁰	≥10 ¹⁰	≥10 ¹⁰	Ω.cm	ASTM D 257

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【 HFC-A1000 】 series

Magnetic Absorber TDS



- Product picture -

Smaller and thin are required with the development of electronic products, it is more important to RFID anti-metal reader and tag, EMI component, Wireless charge products and Electro Magnetic Screen technology etc. Absorber material appeared to solve this problem. It has ultra-thin, soft, easily to roll up and cut performances, it can be custom-made, and also available for laminate with shielding materials like metal foil and fabrics as a multi-layer construction.

FEATURES:

- Soft and ultra-thin
- Insulation properties
- Available in very narrow spaces
- Flexible to cut various shapes
- Excellent performances of absorb electromagnetic radiation noise
- High stickness guaranteed install reliability

APPLICATIONS:

- EMI component
- RFID anti-metal electronic tags and NFC
- Wireless charge products
- Magnetic screen technology

REMARKS:

The material can be laminated with shield layer, Available for custom-made.

The series of products accord with standards of ROHS and HALOGEN.

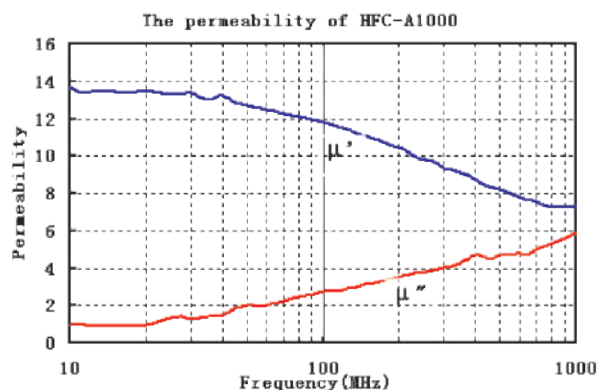
PROPERTIES

Items	Parameter	Test Method
Permeability (μ' @3MHz)	10	IEC 62044-1:2002
Thickness (mm)	0.1~1.0	—
Surface resistance (Ω/inch^2)	$\geq 10^6$	ASTM D257
Adhesion strength (kgf/inch)	≥ 1.0	—
Frequency range (Hz)	RFID:125KHz/134KHz/13.56MHz EMI:10MHz~18GHz	—
Operating temperature ($^{\circ}\text{C}$)	-25~85 (Can be strengthened to 120)	—
UL Certify	UL94V0	—
Package	Roll	—

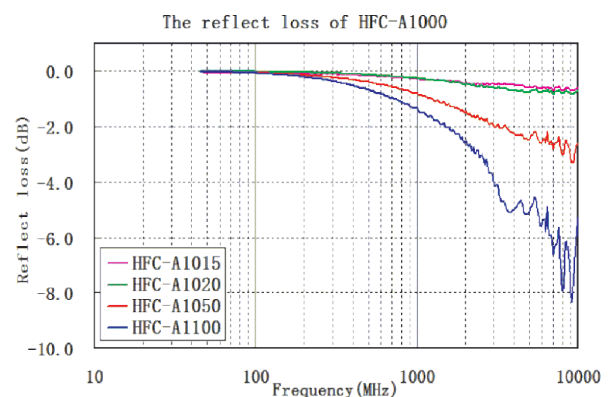
All above data are copyrighted and elaborated by HFC

Magnetic Absorber Properties Test Methods:

Permeability Test [μ' 、 μ'']:



Reflection Loss Test[dB]:



【 HFC-A2000 】 series

Magnetic Absorber TDS



- Product picture -

Smaller and thin are required with the development of electronic products, it is more important to RFID anti-metal reader and tag, EMI component, Wireless charge products and Electro Magnetic Screen technology etc. Absorber material appeared to solve this problem. It has ultra-thin, soft, easily to roll up and cut performances, it can be custom-made, and also available for laminate with shielding materials like metal foil and fabrics as a multi-layer construction.

FEATURES:

- Soft and ultra-thin
- Insulation properties
- Available in very narrow spaces
- Flexible to cut various shapes
- Excellent performances of absorb electromagnetic radiation noise
- High stickness guaranteed install reliability

APPLICATIONS:

- EMI component
- RFID anti-metal electronic tags and NFC
- Wireless charge products
- Magnetic screen technology

REMARKS:

The material can be laminated with shield layer, Available for custom-made.

The series of products accord with standards of ROHS and HALOGEN.

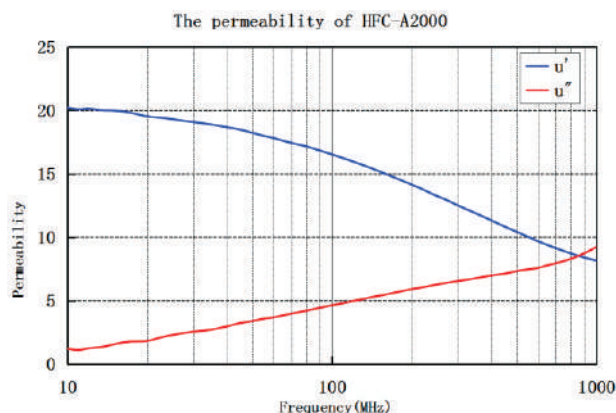
PROPERTIES

Items	Parameter	Test Method
Permeability (μ' @3MHz)	20	IEC 62044-1:2002
Thickness (mm)	0.1~1.0	—
Surface resistance (Ω/inch^2)	$\geq 10^6$	ASTM D257
Adhesion strength (kgf/inch)	≥ 1.0	—
Frequency range (Hz)	RFID:125KHz/134KHz/13.56MHz EMI:10MHz~18GHz	—
Operating temperature ($^{\circ}\text{C}$)	-25~85 (Can be strengthened to 120)	—
UL Certify	UL94V0	—
Package	Roll	—

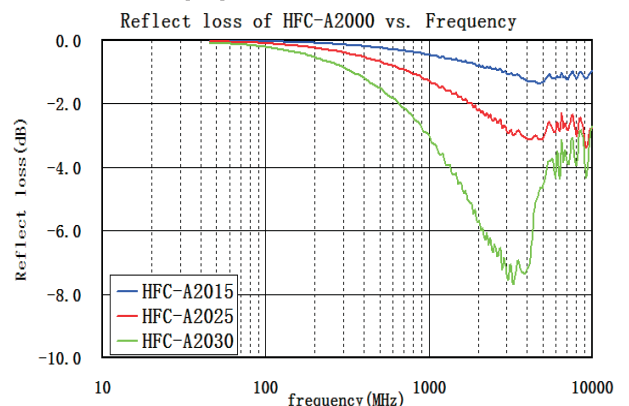
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Magnetic Absorber Properties Test Methods:

Permeability Test [μ' 、 μ'']:



Reflection Loss Test[dB]:



【 HFC-A5000 】 series

Magnetic Absorber TDS



- Product picture -

Smaller and thin are required with the development of electronic products, it is more important to RFID anti-metal reader and tag, EMI component, Wireless charge products and Electro Magnetic Screen technology etc. Absorber material appeared to solve this problem. It has ultra-thin, soft, easily to roll up and cut performances, it can be custom-made, and also available for laminate with shielding materials like metal foil and fabrics as a multi-layer construction.

FEATURES:

- Soft and ultra-thin
- Insulation properties
- Available in very narrow spaces
- Flexible to cut various shapes
- Excellent performances of absorb electromagnetic radiation noise
- High stickness guaranteed install reliability

APPLICATIONS:

- EMI component
- RFID anti-metal electronic tags and NFC
- Wireless charge products
- Magnetic screen technology

REMARKS:

The material can be laminated with shield layer, Available for custom-made.

The series of products accord with standards of ROHS and HALOGEN.

PROPERTIES

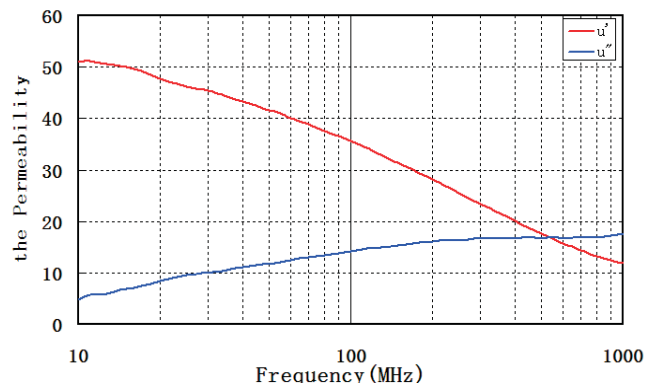
Items	Parameter	Test Method
Permeability (μ' @3MHz)	50	IEC 62044-1:2002
Thickness (mm)	0.03~3.0	—
Surface resistance (Ω/inch^2)	$\geq 10^6$	ASTM D257
Adhesion strength (kgf/inch)	≥ 1.0	—
Frequency range (Hz)	RFID:125KHz/134KHz/13.56MHz EMI:10MHz~18GHz	—
Operating temperature ($^{\circ}\text{C}$)	-25~85 (Can be strengthened to 120)	—
UL Certify	UL94V0	—
Package	Roll	—

All above data are copyrighted and elaborated by HFC

Magnetic Absorber Properties Test Methods:

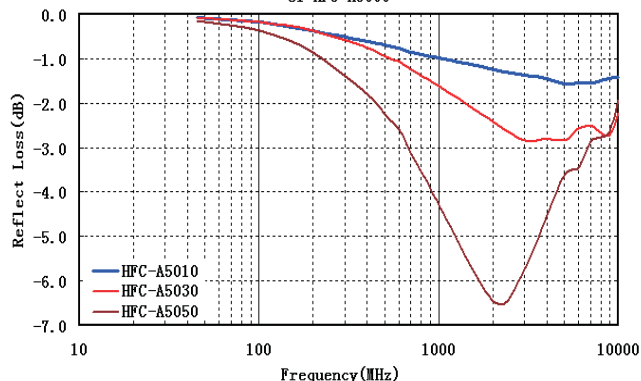
Permeability Test [μ' 、 μ'']:

the Permeability VS. Frequency of HFC-A5000



Reflection Loss Test[dB]:

The reflect loss of different thickness products of HFC-A5000



【 HFC-A12000 】 series

Magnetic Absorber TDS



- Product picture -

Smaller and thin are required with the development of electronic products, it is more important to RFID anti-metal reader and tag, EMI component, Wireless charge products and Electro Magnetic Screen technology etc. Absorber material appeared to solve this problem. It has ultra-thin, soft, easily to roll up and cut performances, it can be custom-made, and also available for laminate with shielding materials like metal foil and fabrics as a multi-layer construction.

FEATURES:

- Soft and ultra-thin
- Insulation properties
- Available in very narrow spaces
- Flexible to cut various shapes
- Excellent performances of absorb electromagnetic radiation noise
- High stickness guaranteed install reliability

APPLICATIONS:

- EMI component
- RFID anti-metal electronic tags and NFC
- Wireless charge products
- Magnetic screen technology

REMARKS:

The material can be laminated with shield layer, Available for custom-made.

The series of products accord with standards of ROHS and HALOGEN.

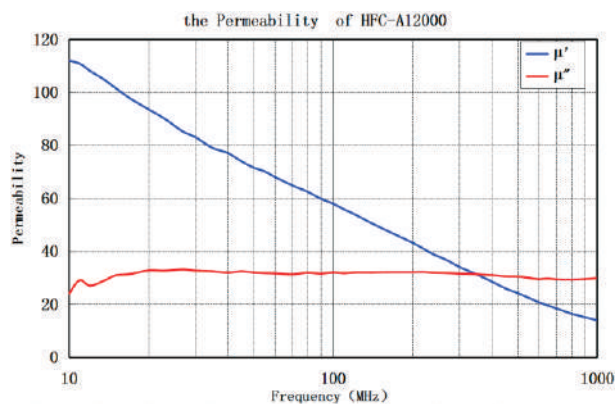
PROPERTIES

Items	Parameter	Test Method
Permeability (μ' @3MHz)	120	IEC 62044-1:2002
Thickness (mm)	0.03~0.5	—
Surface resistance (Ω/inch^2)	$\geq 10^6$	ASTM D257
Adhesion strength (kgf/inch)	≥ 1.0	—
Frequency range (Hz)	RFID:125KHz/134KHz/13.56MHz EMI:10MHz~18GHz	—
Operating temperature ($^{\circ}\text{C}$)	-25~120	—
UL Certify	UL94V-0	—
Package	Sheet/Roll	—

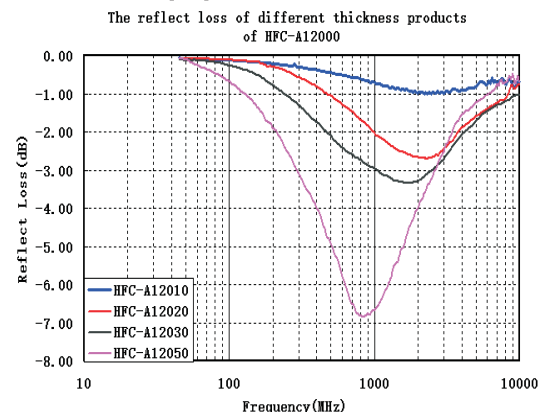
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Magnetic Absorber Properties Test Methods:

Permeability Test [μ' 、 μ'']:



Reflection Loss Test[dB]:



【 HFC-A15000 】 series

Magnetic Absorber TDS



Smaller and thin are required with the development of electronic products, it is more important to RFID anti-metal reader and tag, EMI component, Wireless charge products and Electro Magnetic Screen technology etc. Absorber material appeared to solve this problem. It has ultra-thin, soft, easily to roll up and cut performances, it can be custom-made, and also available for laminate with shielding materials like metal foil and fabrics as a multi-layer construction.

FEATURES:

- Soft and ultra-thin
- Insulation properties
- Available in very narrow spaces
- Flexible to cut various shapes
- Excellent performances of absorb electromagnetic radiation noise
- High stickness guaranteed install reliability

APPLICATIONS:

- EMI component
- RFID anti-metal electronic tags and NFC
- Wireless charge products
- Magnetic screen technology

REMARKS:

The material can be laminated with shield layer, Available for custom-made.

The series of products accord with standards of ROHS and HALOGEN.

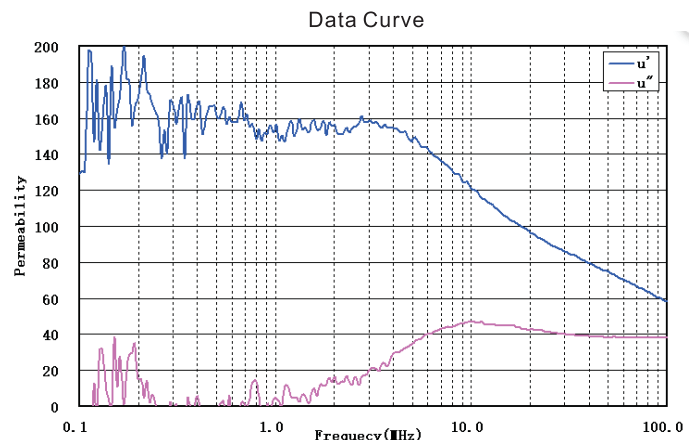
PROPERTIES

Items	Parameter	Test Method
Permeability (μ' @3MHz)	150	IEC 62044-1:2002
Thickness (mm)	0.03~0.1	—
Surface resistance (Ω/inch^2)	$\geq 10^6$	ASTM D257
Adhesion strength (kgf/inch)	≥ 1.0	—
Frequency range (Hz)	EMI:100MHz~3GHz	—
Operating temperature ($^{\circ}\text{C}$)	-25~120	—
UL Certify	UL94V-0	—
Package	Sheet	—

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Magnetic Absorber Properties Test Methods:

The Permeability VS Frequency:



【 HFC-A18000 】 series

Magnetic Absorber TDS



Smaller and thin are required with the development of electronic products, it is more important to RFID anti-metal reader and tag, EMI component, Wireless charge products and Electro Magnetic Screen technology etc. Absorber material appeared to solve this problem. It has ultra-thin, soft, easily to roll up and cut performances, it can be custom-made, and also available for laminate with shielding materials like metal foil and fabrics as a multi-layer construction.

FEATURES:

- Soft and ultra-thin
- Insulation properties
- Available in very narrow spaces
- Flexible to cut various shapes
- Excellent performances of absorb electromagnetic radiation noise
- High stickness guaranteed install reliability

APPLICATIONS:

- EMI component
- RFID anti-metal electronic tags and NFC
- Wireless charge products
- Magnetic screen technology

REMARKS:

The material can be laminated with shield layer, Available for custom-made.

The series of products accord with standards of ROHS and HALOGEN.

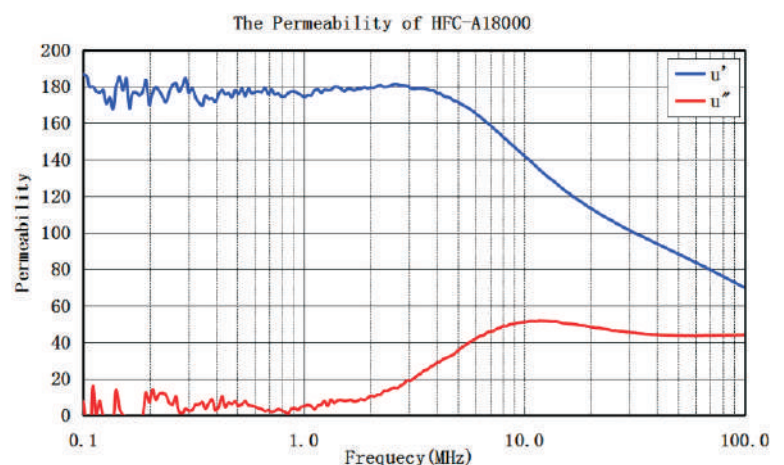
PROPERTIES

Items	Parameter	Test Method
Permeability (μ' @3MHz)	180	IEC 62044-1:2002
Thickness (mm)	0.03~0.1	—
Surface resistance (Ω/inch^2)	$\geq 10^6$	ASTM D257
Adhesion strength (kgf/inch)	≥ 1.0	—
Frequency range (Hz)	EMI: 100MHz~3GHz	—
Operating temperature ($^{\circ}\text{C}$)	-25~120	—
UL Certify	UL94V-0	—
Package	Sheet	—

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Magnetic Absorber Properties Test Methods:

The Permeability VS Frequency:



【 HFC-A25000 】 series

Magnetic Absorber TDS



Smaller and thin are required with the development of electronic products, it is more important to RFID anti-metal reader and tag, EMI component, Wireless charge products and Electro Magnetic Screen technology etc. Absorber material appeared to solve this problem. It has ultra-thin, soft, easily to roll up and cut performances, it can be custom-made, and also available for laminate with shielding materials like metal foil and fabrics as a multi-layer construction.

FEATURES:

- Soft and ultra-thin
- Insulation properties
- Available in very narrow spaces
- Flexible to cut various shapes
- Excellent performances of absorb electromagnetic radiation noise
- High stickness guaranteed install reliability

APPLICATIONS:

- EMI component
- RFID anti-metal electronic tags and NFC
- Wireless charge products
- Magnetic screen technology

REMARKS:

The material can be laminated with shield layer, Available for custom-made.

The series of products accord with standards of ROHS and HALOGEN.

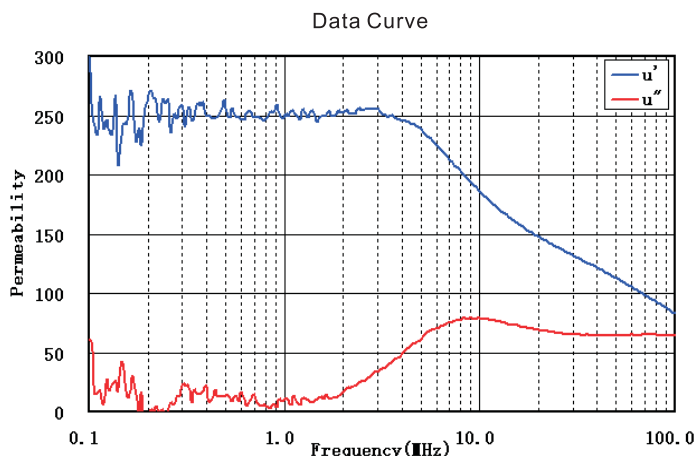
PROPERTIES

Items	Parameter	Test Method
Permeability (μ' @3MHz)	250	IEC 62044-1:2002
Thickness (mm)	0.03~0.1	—
Surface resistance (Ω/inch^2)	$\geq 10^6$	ASTM D257
Adhesion strength (kgf/inch)	≥ 1.0	—
Frequency range (Hz)	EMI: 100MHz~3GHz	—
Operating temperature ($^{\circ}\text{C}$)	-25~120	—
UL Certify	UL94V-0	—
Package	Sheet	—

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Magnetic Absorber Properties Test Methods:

The Permeability VS Frequency:



SMT GASKET series

【 Shielding Material 】

DATA SHEET



- Product picture -

FEATURES:

- Competitive price and effective productivity by using SMT
- Strong bonding force after soldering on PCB by reflow heating
- Accurate package for effective production
- Pass reliability test
- Excellent conductive property
- Good compressibility and resilience
- Good performance on EMI
- Being resistant to high temperature and humidity
- RoHS compliant, halogen free

APPLICATIONS:

- The small and thin products are more often used in handy device, camera module, precision circuit, etc, while the bigger and wider products are commonly applied in Monitor, automatic circuits and specific design.
- They are widely used in LCD, PDP, cellphone, navigation, monitor, FPCB, antenna, touch panel, digital camera, keyboard, etc.

USE CONDITION:

- The common work temperature is from -40 °C to 180 °C
- The temperature for soldering is 260±10 °C (for 2 minutes or shorter)

PACKING:

Advanced automatic encapsulation method can protect the product from damages during transportation. Roll packing design is easy to transport and store. Packing quantity in integer of each roll can be classified into 1000 pcs, 1500 pcs and 2000 pcs (or according to the requirements of customer). It also can be customized in bulk. The biggest advantage of this product package is that it both satisfies with fully automatic and semi-automatic production line when products are assembled.

SMT gasket is a conductive terminal which can be soldered on Printed Circuit Board panel by surface mount technology (SMT). It is effective to reduce EMI noise and physical shocking, support the upper layer, fill the space, conduct the electrons and so on. It can be used in various service environment. Our products meet the RoHS requirements. Comparing with the traditional SMT gasket-the metal gasket, it is not easy to break off and take off. Besides, it is more competitive in price.

PROPERTIES

Items	Parameter		Unit	Test Method
	A	B		
Color	Silver	Silver	-	Visual
Surface Resistance	< 0.05	< 0.05	Ω	GB/T 2423
Vertical Resistance	< 0.05	< 0.05	Ω	GB/T 2423
Resilience Ratio	≥ 95	≥ 85	%	ASTM D 374
Soldering Strength	≥ 5	≥ 5	N	DPS-5R(MADA)
Heat Resistance	≤ 0.05	≤ 0.05	Ω	GB/T 2423.2
Humid Resistance	≤ 0.05	≤ 0.05	Ω	GB/T 2423.3
Deformation	≤ 10	≤ 10	%	ASTM D 5947
Hardness	60 ± 10 (Shore A)	20 ± 3 (Shore C)	Shore	ASTM D 2240
UL-Certification	V-1	V-0	-	UL94

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I/O EMI GASKET series

【 Shielding Material 】

DATA SHEET



- Product picture -

FEATURES:

- Good conductivity
- Good compressibility and resilience
- Good performance on EMI shield effectiveness
- RoHS compliant, halogen free
- Extensive working temperature (-40~70°C)

APPLICATIONS:

Aerospace, telecom and high speed computer which requires I/O shielding interfaces.

The I/O gasket is processed from conductive foam. I/O gaskets are designed for electromagnetic shielding at the input and output of various electronics. Conductive foam gaskets in different thickness, width or material can be specially designed and customized, then be punched into various shapes for different electronics.

PROPERTIES

Items	Parameter	Unit
Surface Resistance	0.05	Ω/inch^2
Frequency Range(Test) (10MHz-1GHz)	> 85	dB
Resilience	≥ 80	%
Vertical Resistance	≤ 0.05	Ω

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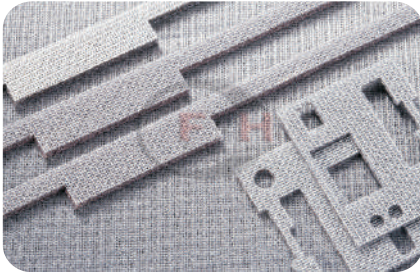
OVERVIEW:

- Our products can be customized into various shapes and specifications, so please contact us for your specific inquiries.
- Customers can have specific requirements for raw materials including adhesives such as 3M and Nitto.

XYZ AXIS CONDUCTIVE FOAM series

【 Shielding Material 】

DATA SHEET



- Product picture -

FEATURES:

- Excellent conductivity
- Flexible and easy to process for various designs
- Good compressibility and resilience
- Good shielding effectiveness
- Easy to paste and peel off
- RoHS compliant, halogen free

APPLICATIONS:

- The small and thin products are often used in handy device, camera module, precision circuit, etc, while the bigger and wider products are commonly applied in Monitor, automatic circuits and specific design.
- They are widely used in LCD, PDP, cellphone, navigation, monitor, FPCB, antenna, touch panel, digital camera, keyboard, etc.

XYZ axis conductive gasket is mainly made up of conductive foam and conductive fabric. The foam is coated with metal material by vacuum electroplating. With competitive price and three-dimensional shielding effectiveness, it performs as good conductivity as metal. It is difficult to make FOF gaskets in very small size, but it is easier to make conductive foam gasket for tight space.

PROPERTIES

Items	Parameter	Unit	Test Method
Color	Gray/Black	-	-
Thickness	0.15~5	mm	FZ/T01003-1991
Surface Resistance	≤ 0.2	Ω/inch^2	ASTM F 390
Vertical Resistance	≤ 0.2	Ω	ASTM F 390
Shielding Effectiveness Working Temp	≤ 0.2	$^{\circ}\text{C}$	-

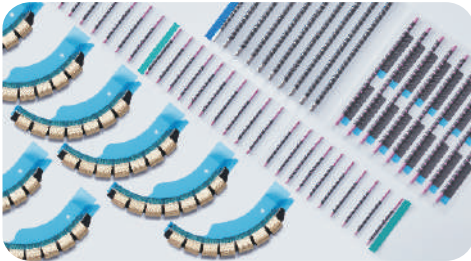
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CONDUCTIVE FABRIC OVER AIR GASKET series

【 Shielding Material 】

DATA SHEET



- Product picture -

FEATURES:

- Excellent conductive performance
- Excellent manufacturability
- Molded without thermoplastics
- Good shielding effectiveness
- RoHS compliant, halogen free

APPLICATIONS:

widely used in Apple mobile phones and other electronic products.

TOLERANCE:

- L/W/H(mm): $W/L/H < 20\text{mm} \pm 0.3\text{mm}$
 $20 \leq W/L < 50 \pm 0.5\text{mm}$
 $50 \leq W/L < 100 \pm 0.68\text{mm}$
 $L \geq 100 \pm 3\text{mm}$

Conductive Fabric Over Air Gasket is made of conductive fabric which can be cut or packed with conductive adhesive .It is used for electronic products such as mobile phone,computer,TV,communication equipment and so on.

PROPERTIES

Items	Parameter	Unit	Test Method
Surface Resistance	< 0.05	Ω/inch^2	ASTM F 390
Shielding effectiveness (10MHz-3GHz)	> 85	dB	ASTMD 4935-99
Working Temp	-10~80	$^{\circ}\text{C}$	FZ/T01003-1992



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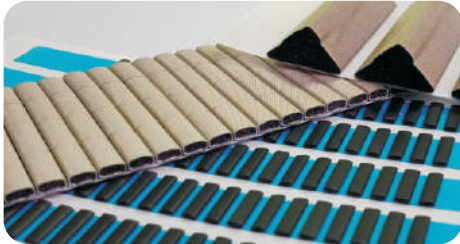
PACKING:

Products is carried by PET and packed by plastic trays,so it is easy to checkits number with regular capacity in addition.There are two hardboard to protect products from damage during transportation.

EMI GASKET series

【 Shielding Material 】

DATA SHEET



- Product picture -

FEATURES:

- Excellent conductivity
- Flexible and easy to process for various designs
- Good compressibility and resilience
- Good shielding effectiveness
- Easy to paste and peel off
- RoHS compliant, halogen free

APPLICATIONS:

- The small and thin products are often used in handy devices, camera module, precision circuit, etc. Bigger and wider products are commonly applied in Monitor, automatic circuits and specific design.
- They are widely used in LCD, PDP, cellphone, navigation, monitor, FPCB, antenna, touch panel, digital camera, keyboard, etc.

FOF gasket is a kind of conductive foam wrapped in conductive fabric. It has good surface conductivity and can be easily fixed on devices for EMI. With different shapes, installation methods and UL grades, it can be divided into common conductive foam, nickel-plated and copper-plated conductive foam, gold-plated conductive foam, carbon-plated conductive foam, tin-plated conductive foam, conductive aluminum foil foam, conductive copper foil foam, I/O conductive foam pad, etc. They have excellent electrical and elastic properties, shock absorption and shielding effect and can be used in filling and grounding. It is widely applied in PDP TV, LCD display, LCD TV, mobile phone, notebook computer, MP3, communication equipments, medical equipment and other electronic products as well as military and aerospace fields.

PROPERTIES

Item	Paramter			Unit	Test method
	GS00705C	GR00790C	GR27113A		
Color	Grey	Grey	Black	-	Visual
Specifications	13.43*7.33*38	4*2*8	2.17*0.66*7.94	mm	FT/T01003-1991
Adhesion Strength	≥1	≥1	≥1	Kgf/inch	GB/T279-1998
Surface Resistance	≤0.2	≤0.2	≤0.2	Ω/inch ²	ASTM F 390
Vertical Resistance	≤0.2	≤0.2	≤0.2	Ω/inch ²	ASTM F 390
Shielding effectiveness (10MHz-3GHz)	-40-70	-40-70	-40-70	°C	-

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